BRCS3415MC

Rev.B .Dec.-2024

DATA SHEET

/ Descriptions

SOT23-3 Ṃ Ṃ Ŀ S ǆ MOS ʃ ᾧ Ẓ ˥

P- CHANNEL MOSFET in a SOT23-3 Plastic Package.

/ Features

V_{DS} (V)=-20V I_D =-5.0A(V_{GS}= ± 10V)

$R_{DS(ON)}$< 40 mΩ,V_{GS}= -4.5V

$R_{DS(ON)}$< 53 mΩ,V_{GS}= -2.5V

ŋ̀ ɾ β HF Product.

/ Applications

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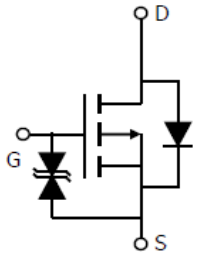
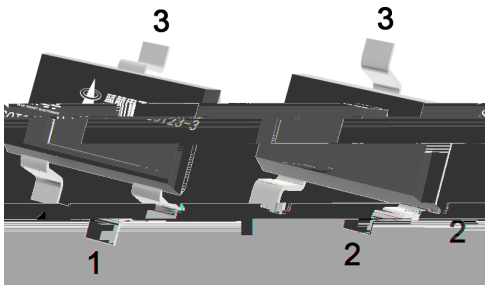
Load switch ı Battery protection.

/ Equivalent Circuit



/ Pinning



PIN1 χ G PIN 2 χ S PIN 3 χ D

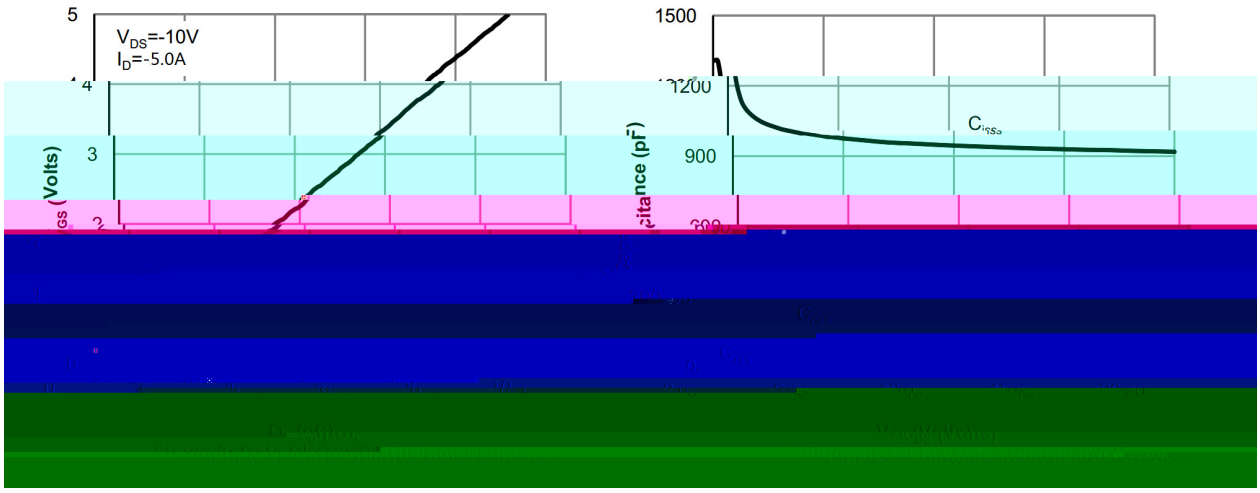
/ Marking

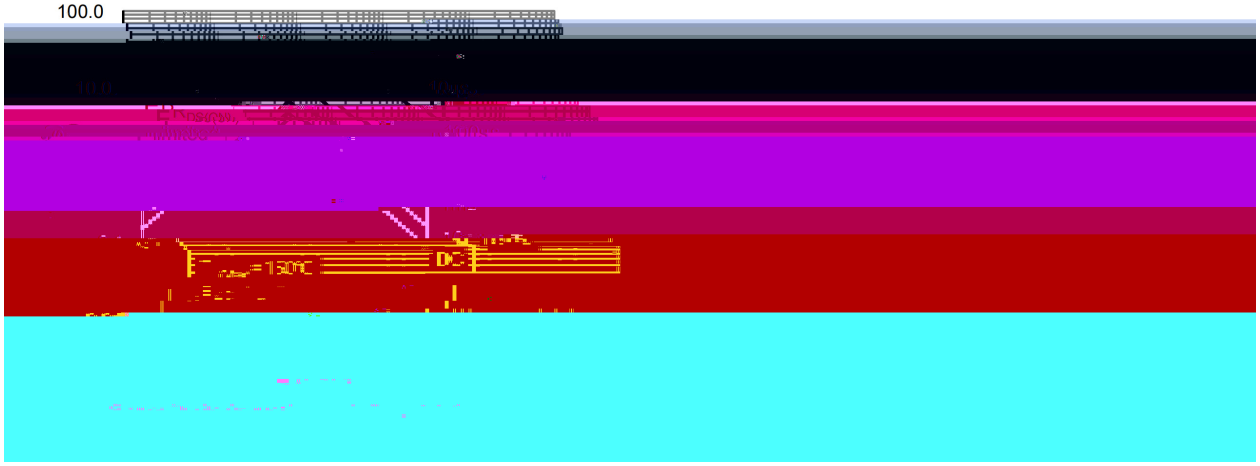
Marking	AFH

v ̈Ω Parameter	ϒ N Symbol	̈Ω Ö Rating	D Ĥ Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 10	V
Drain Current-Continuous	I_D	-5.0	A
Drain Current-Pulsed	I_{DM}		

/ Electrical Characteristic Curve

/ Electrical Characteristic Curve





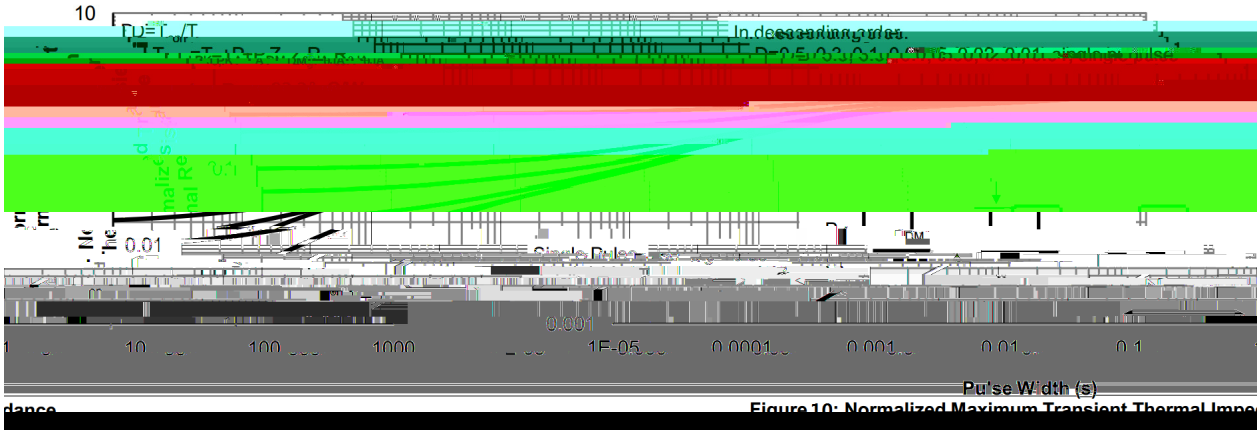
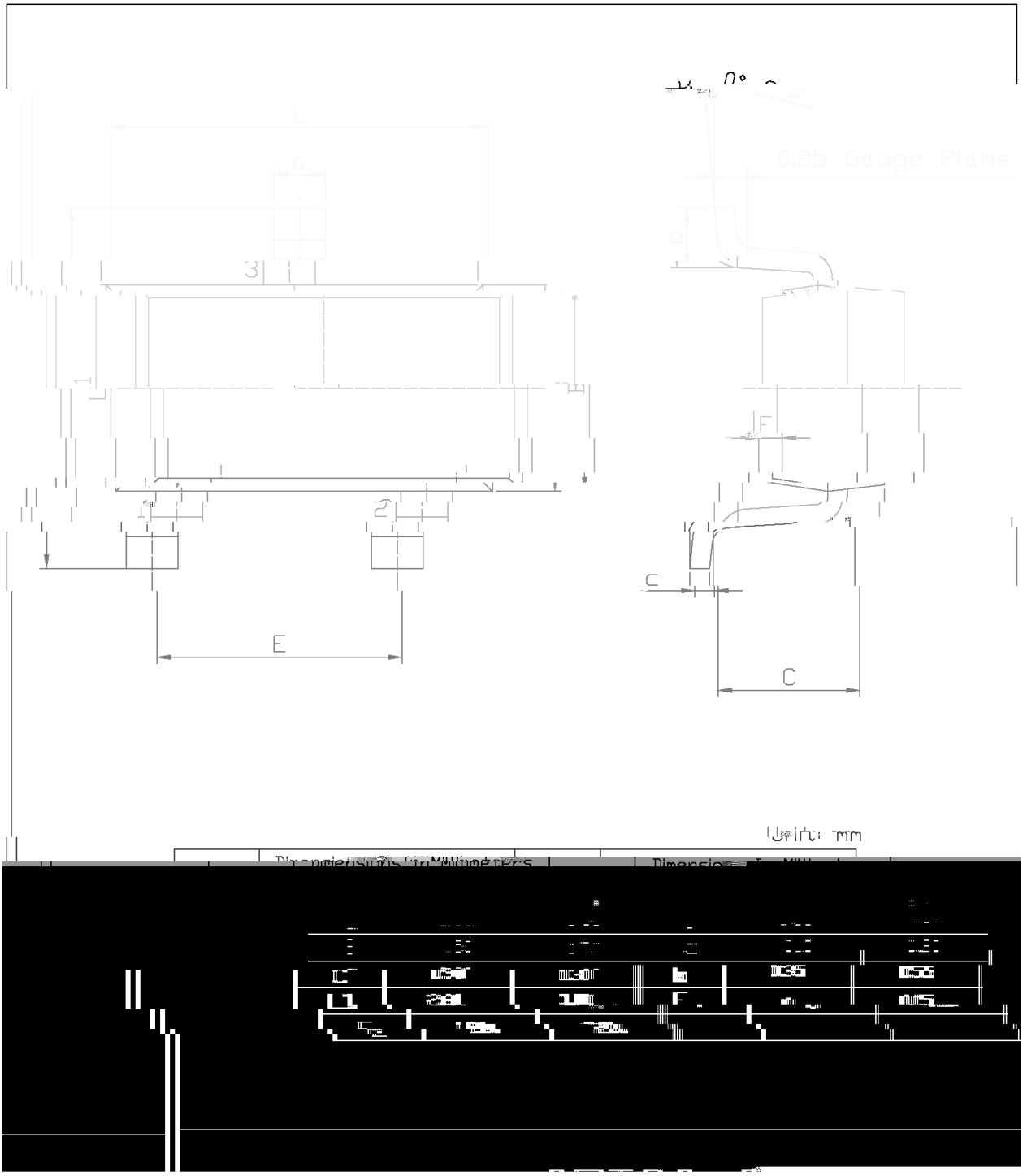
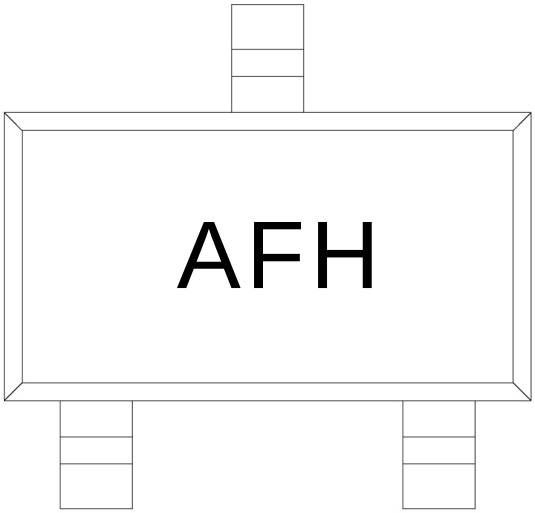


Figure 10: Normalized Maximum Transient Thermal Impe

/ Package Dimensions



/ Marking Instructions



ب ˝ χ

H: ⿰ᄎ ʒ ᴵᴵ ᴵ

AF: ⿰ᄎ ʒ ᴺ ᴵ

Note:

H: Company Code

AF χ Product Type Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ

1 أ ♬ □ ỷ 150 Ḱ 180 ɬ ı `H ڑ 60 Ḱ 90sec;

2 Š Ö □ ỷ 245 ° 5 ɬ ı `H ڑ ˙Y ⅄ ⅏ 5 ° 0.5sec;

3 ì ˙ ⅂ ˛ ɔ ه ỷ ⅏ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:150~180 ɬ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ɬ `H ڑ χ 10 ° 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

ɔ` γ ⊢ / REEL

Package Type	Units	Dimension	(unit mm³]Q9ZÈH)9˝ty¶ZGty¶ZHeyeGt¶ZGt